

## ABSTRACT

5 A pad conditioning system for conditioning a polishing pad in conjunction with a workpiece polishing operation includes a pad conditioning head coupled with a positioning unit. The pad conditioning head includes a plurality of abrasive particles protruding from a surface of the pad conditioning head. The positioning unit is configured to move the surface into contact with a polishing pad. The pad conditioning system also includes a liquid supply nozzle. The liquid supply nozzle is configured to selectively discharge liquid proximate to the abrasive particles that are in contact with the polishing pad to minimize frictional wear of the abrasive particles.